

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claim 16 and AMEND claims 11, 17, 21 and 24 in accordance with the following:

1-10. (Cancelled)

11. (Currently Amended) A circuit device provided on a substrate and comprising:  
a single active semiconductor component arranged on the substrate and having an outer electrical contact surface, the single active semiconductor component being a power semiconductor component; and

at least one electrical connection line on the substrate to contact with the outer electrical contact surface of the single active semiconductor component,

wherein

the electrical connection line is part of at least one discrete passive electrical component arranged on the substrate, the electrical connection line contacts the outer electrical contact surface at an electrical contact, such that the electrical contact faces away from the substrate, and

a layer of electrically insulating film is laminated onto the semiconductor component and the substrate in such a way that the electrical contact is exposed.

12. (Previously Presented) The circuit device in accordance with claim 11, wherein  
the discrete passive electrical component is a capacitor, and  
the electrical connection line is an electrode of the capacitor.

13. (Previously Presented) The circuit arrangement in accordance with claim 11,  
wherein

the discrete passive electrical component is a coil , and  
the electrical connection line is a winding of the coil.

14. (Previously Presented) The circuit device in accordance with claim 11, wherein the discrete passive electrical component is an electrical resistor, and the electrical connection line is a wire resistor.
15. (Previously Presented) The circuit device in accordance with claim 11, wherein the discrete passive electrical component is a part of a sensor of a physical variable.
16. (Cancelled)
17. (Currently Amended) The circuit device in accordance with claim ~~16~~11, wherein the power semiconductor component is selected from the group consisting of MOSFETs, IGBTs and bipolar transistors.
18. (Previously Presented) The circuit device in accordance with claim 14, wherein the discrete passive electrical component is a part of a sensor of a physical variable.
19. (Previously Presented) The circuit arrangement in accordance with claim 18, wherein the semiconductor component is a power semiconductor component.
20. (Previously Presented) The circuit device in accordance with claim 19, wherein the power semiconductor component is selected from the group consisting of MOSFETs, IGBTs and bipolar transistors.
21. (Currently Amended) A method for producing a circuit device, comprising:  
producing a single active semiconductor component on a substrate, the single active semiconductor component having an outer electrical contact surface facing away from the substrate, the single active semiconductor component being a power semiconductor component;  
and  
producing an electrical connection line that contacts the outer electrical contact surface of the semiconductor component, the electrical connection line being part of a discrete passive electrical component, the electrical connection line contacting the outer electrical contact surface at an electrical contact, such that the electrical contact faces away from the substrate, and

laminating a layer of electrically insulating film onto the semiconductor component and the substrate in such a way that the electrical contact is exposed.

22. (Cancelled)

23. (Previously Presented) The method in accordance with claim 21, wherein the layer of electrically insulating film is first applied, and then the electrical contact is exposed by opening a window in the electrically insulating material.

24. (Currently Amended) A circuit device provided on a substrate and comprising:  
a single active semiconductor component arranged on the substrate and having an outer electrical contact surface, the single active semiconductor component being a power semiconductor component; and

at least one electrical connection line on the substrate to contact with the outer electrical contact surface of the single active semiconductor component,

wherein

the electrical connection line is part of at least one discrete passive electrical component arranged on the substrate, the electrical connection line contacts the outer electrical contact surface at an electrical contact, such that the electrical contact faces away from the substrate, and

a layer of electrically insulating film is laminated onto at least two surfaces of the semiconductor component and the substrate in such a way that the electrical contact is exposed.